

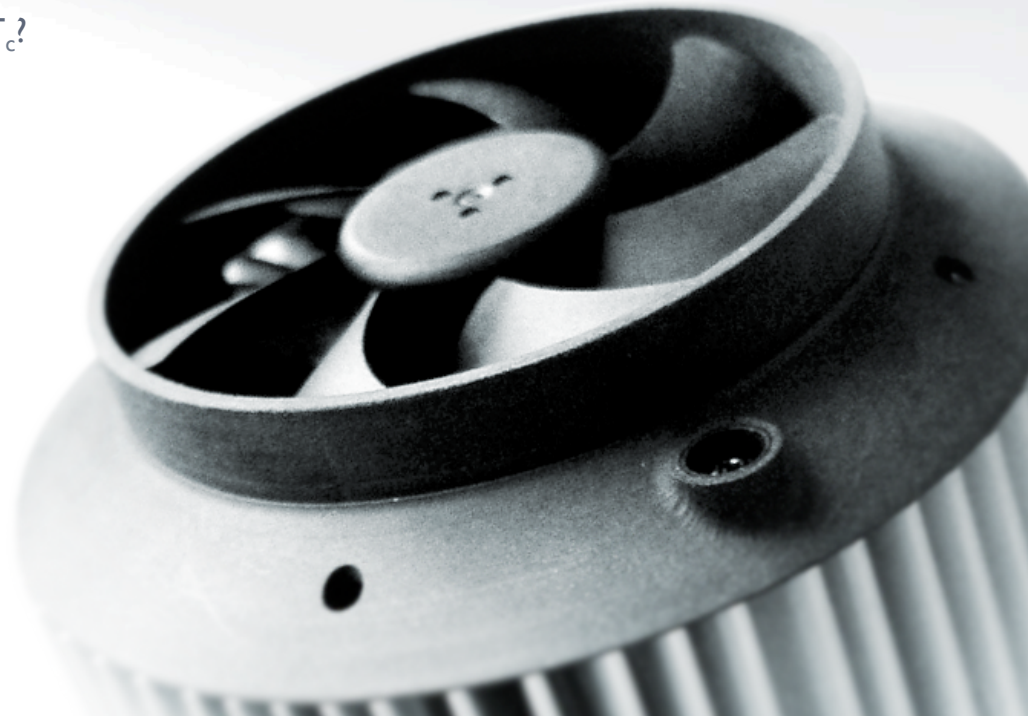
# Thermal Design Guide V2.3

Fortimo LED SLM platform



# Contents

- Thermal specifications
- How to measure  $T_{\text{case}}$  at its critical temperature point  $T_c$ ?
- Thermal interface materials (TIM)
- Designing a passive cooled luminaire
- Designing an active cooled luminaire
- Complementary partners for thermal solutions  
(passive/ active)



# Thermal specifications Fortimo SLM platform

Fortimo SLM Platform	800 Lm	1100 Lm	1500 Lm	2000 Lm	3000 Lm	Lexel TW	Lexel RGB
Electrical power (typical)	11 W	17 W	20 W	32 W	43 W	22 W	25 W
Dissipated thermal power (typical)	9 W	14 W	17 W	27 W	36 W	18 W	20 W
Max. T <sub>case</sub> of module	←			65 °C	→		
Max. ambient temperature	←			35 °C	→		
Thermal impedance requirement T <sub>case</sub> to T <sub>ambient</sub>	<3.33 °C/W	<2.14 °C/W	<1.76 °C/W	<1.11 °C/W	<0.83 °C/W	<1.67 °C/W	<1.50 °C/W

Minimum performance requirement for total cooling solution including TIM, better performance is always preferred and recommended

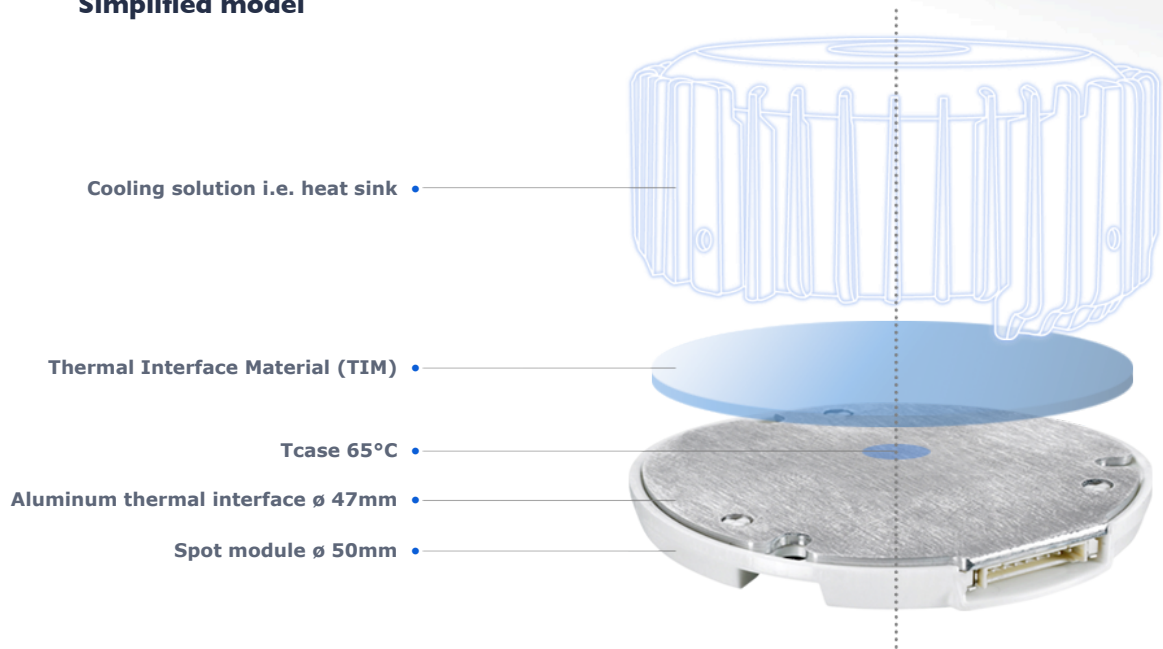


# Thermal specifications Fortimo SLM platform

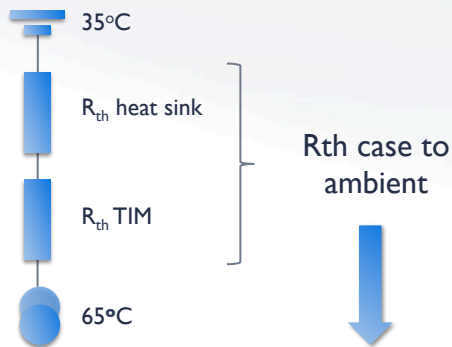
Fortimo SLM thermal specifications :

- Tcase maximum +30°C above ambient
- Max ambient 35°C
- Maximum 65°C Tcase at 35°C ambient

## Simplified model



## Thermal network

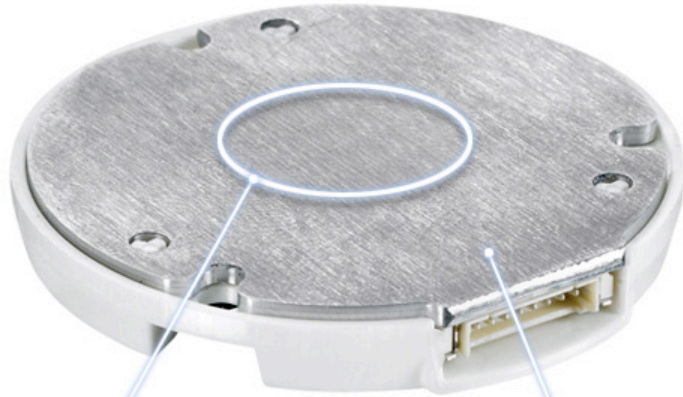


SLM 800lm 9W => Rth case to ambient  $\leq 3.33$  (°C/W)  
SLM 1100lm 14W => Rth case to ambient  $\leq 2.14$  (°C/W)  
SLM 1500lm 17W => Rth case to ambient  $\leq 1.76$  (°C/W)  
SLM 2000lm 27W => Rth case to ambient  $\leq 1.11$  (°C/W)  
SLM 3000lm 36W => Rth case to ambient  $\leq 0.83$  (°C/W)  
SLM LX TW 18W => Rth case to ambient  $\leq 1.67$  (°C/W)  
SLM LX RGB 20W => Rth case to ambient  $\leq 1.50$  (°C/W)  
Note: this includes the TIM



# Thermal specifications Fortimo SLM platform

- A maximum surface temperature of 65°C to be guaranteed on the interface between the 'Module' and the 'TIM + cooling solution' at maximum ambient of 35°C
- All types of Fortimo SLM drivers will dim when a temperature over 65°C is sensed by the SLM module



**Max. Tcase 65°C**  
Specification on surface

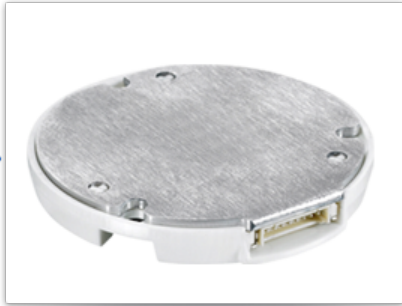
**Aluminum thermal  
interface ø47 mm**



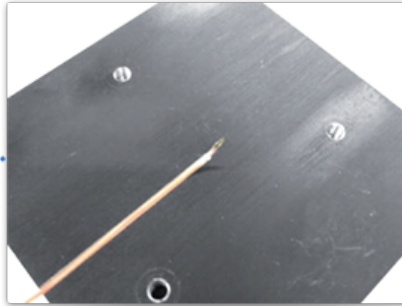
**3 screw holes for attachment of module  
onto heatsink (M3, bolt circle ø42mm)**

# How to measure critical temperature point $T_c$ ?

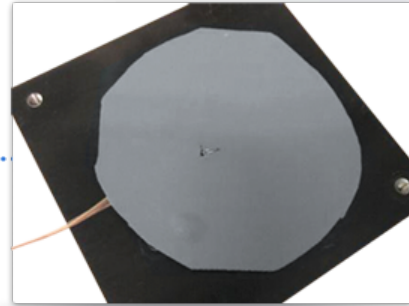
- The  $T_{case}$  should be measured at its critical temperature point, **centre point at the bottom of the module**
- This can be done **by making a thin v-groove in the heat sink or a small drill hole in the heat sink** to reach bottom of the module at its critical temperature point, make sure to measure the bottom of the module and not the TIM



Critical temperature point  $T_c$



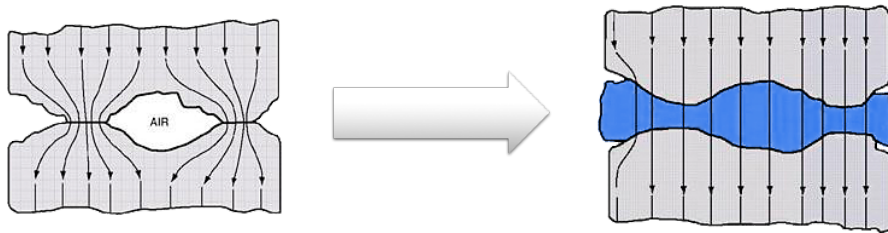
Thin v-groove in the heatsink  
to embed a thermocouple



Tip of thermocouple sticking  
out on top of the thermal pad  
(TIM)

# Thermal Interface Materials (TIM)

- Function is to reduce thermal impedance between two solid surfaced
- Replaces air (thermal insulator  $c=0.024\text{W/mK}$ ) by filling the gaps with better conductive thermal interface material (order  $c=1\text{W/mK}$ )



- In general:
  - Thermal pastes performs better than thermal pads
  - The higher the thermal conductivity the better
  - The thinner the TIM the better

- **In practice:**

- Actual thermal impedance [ $^{\circ}\text{C/W}$ ] of TIM in application is more important than conductivity of material
- Each thermal interface can have a significant contribution to the total thermal impedance of module to ambient
- Limiting the # of thermal interfaces from module to ambient is strongly recommended)

# Contact information complementary partners

## Thermal interface materials (TIM)

- The Bergquist Company

[www.bergquistcompany.com](http://www.bergquistcompany.com)

### North American Headquarters

18930 W. 78th Street

Chanhassen, MN 55317 USA

### Contact person for Europe

Nico Bruijn

Phone: +31 35 538 0684

Cell: +31 6 5316 0688

E-mail: [n.bruijnis@bergquist-europe.com](mailto:n.bruijnis@bergquist-europe.com)

- Chomerics

[www.chomerics.com](http://www.chomerics.com)

### Chomerics North America

Parker Hannifin Corp.

77 Dragon Court

Woburn, MA 01801 USA

### Contact person for Europe

Luc Coupet

Phone: +33 134323900

Cell: +33 670765480

E-mail: [luc.coupet@parker.com](mailto:luc.coupet@parker.com)

- Laird Technologies

[www.lairdtech.com](http://www.lairdtech.com)

### Corporate Headquarters

Laird Technologies (Corporate)

16401 Swingley Ridge Road

Suite 700

Chesterfield, MO 63017

### Contact person for Europe

Philip Blazdell

Phone: +49 803124600

Cell: +44 7595710316

E-mail: [philip.blazdell@lairdtech.com](mailto:philip.blazdell@lairdtech.com)



# Designing a passive cooled luminaire

Design based on Fortimo SLM I 100lm:

- Performance requirement cooling  $R_{th} < 2.14 \text{ } ^\circ\text{C/W}$

$$R_{th \text{ case to ambient}} = \frac{T_{\text{case}} - T_{\text{amb}}}{\text{Thermal dissipation}} = \frac{65^\circ\text{C} - 35^\circ\text{C}}{14\text{W}} = 2.14 \frac{^\circ\text{C}}{\text{W}}$$

$$R_{th \text{ case to ambient}} = R_{th \text{ heatsink}} + R_{th \text{ TIM}}$$

$$R_{th \text{ case to ambient}} = \frac{1}{h_{tc} * \text{effective cooling surface}}$$

- Assuming a conservative heat transfer coefficient ( $h_{tc}$ ) =  $5 \text{ W/m}^2\text{K}$  and the contribution of the thermal interface material  $R_{th \text{ TIM}} = 0.1 \text{ } ^\circ\text{C/W}$  a first estimate of the required cooling surface can be calculated

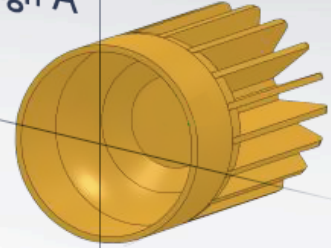
$$\text{Minimum cooling surface} = \frac{1}{h_{tc} * R_{th \text{ heatsink}}} = \frac{1}{5 \frac{\text{W}}{\text{m}^2\text{K}} * 2.04^\circ\text{C/W}} = 0.098\text{m}^2$$



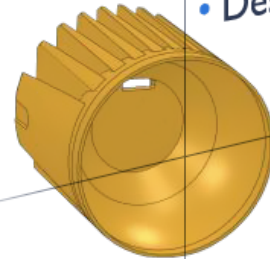
# Design of Experiments (DoE)

- Based on the previous calculation a minimum surface area of  $0.098 \text{ m}^2$  is required
- This corresponds to a cylinder of  $\varnothing 120\text{mm}$  and  $260\text{mm}$  long
- In order to reduce overall size of the luminaire, cooling fins should be introduced
- To optimization the thermal performance a DoE should be set up
- Example of simple DoE with CFD analysis:
  - Comparison of Design A and B
  - Effect of thermal radiation, blank metal surface or black anodized

• Design A



• Design B



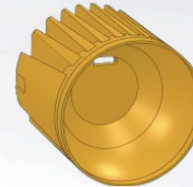
# Design of Experiments (DoE)

## Results DoE

### Design A



### Design B



Area (m <sup>2</sup> )	0.236	0.236	0.158	0.158
Emissivity (-)	0.1	0.9	0.1	0.9
R <sub>th heatsink</sub> (°C/W)	1.33	0.99	1.76	1.39
HTC average (W/m <sup>2</sup> K)	3.2	4.3	3.6	4.6

A DoE can of course be much more extensive:

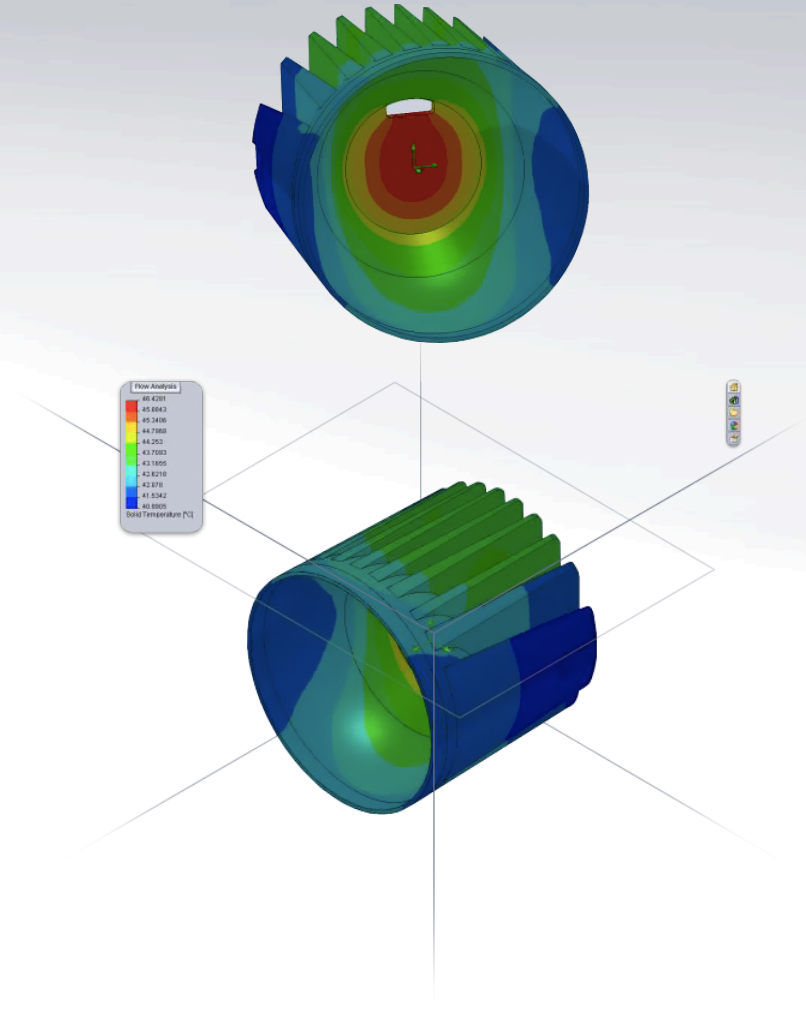
- Different material (thermal conductivity)
- Orientation; horizontal or vertical (here horizontal is assumed as worst case, so both heat sinks will also work in vertical orientation)



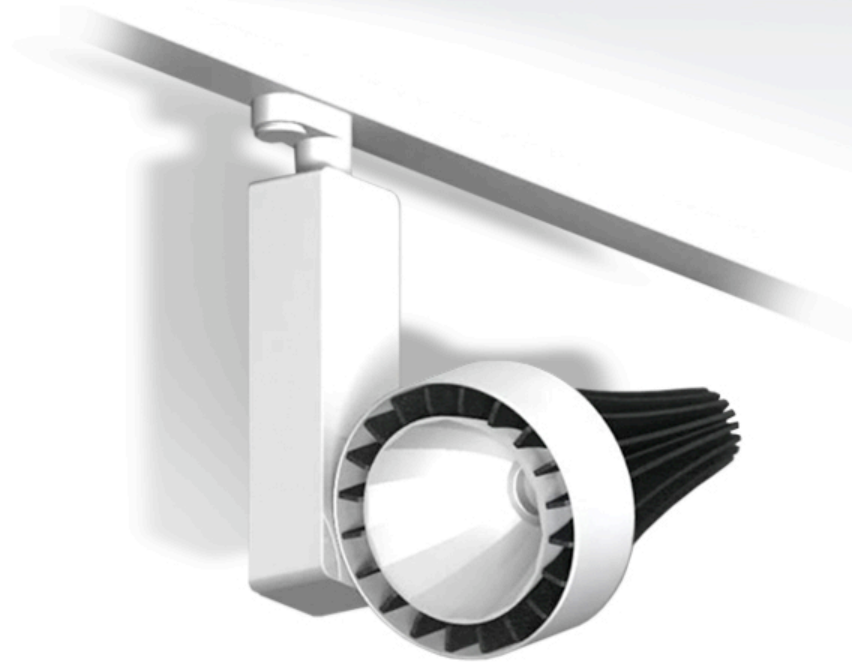


# Detailed analysis

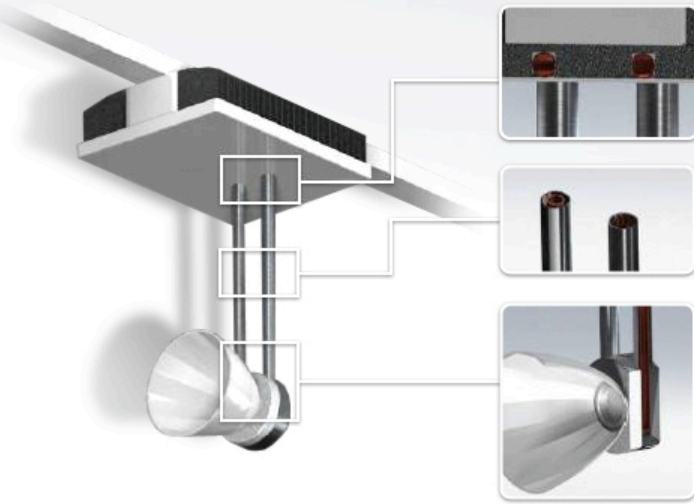
- Both designs are feasible, but choice is to focus on design B
- The fins are placed in line with the flow direction for maximum efficiency, this way it is possible to keep the overall luminaire size and weight small.
- Analysis with CFD can further optimize the design:
  - i.e. optimization of fin thickness and fin spacing



# Passive cooled luminaire designs



- After design optimization a passive luminaire design could look like this:



- Another passive cooled design, but with heat pipes:

# Some design guidelines for passive cooling

- Limit the # of thermal interfaces in the thermal path from module to ambient => **strongly recommended**
- Thick fins conduct heat better than thin fins
- Large spacing between fins is better than small spacing between fins
- Make cooling surfaces more effective by using proper conductive materials, appropriate thickness and sound orientation
- Thermal radiation plays a significant role => **anodized surfaces are preferred over blank surfaces**



# Designing an active cooled luminaire

Design based on Fortimo SLM 2000lm:

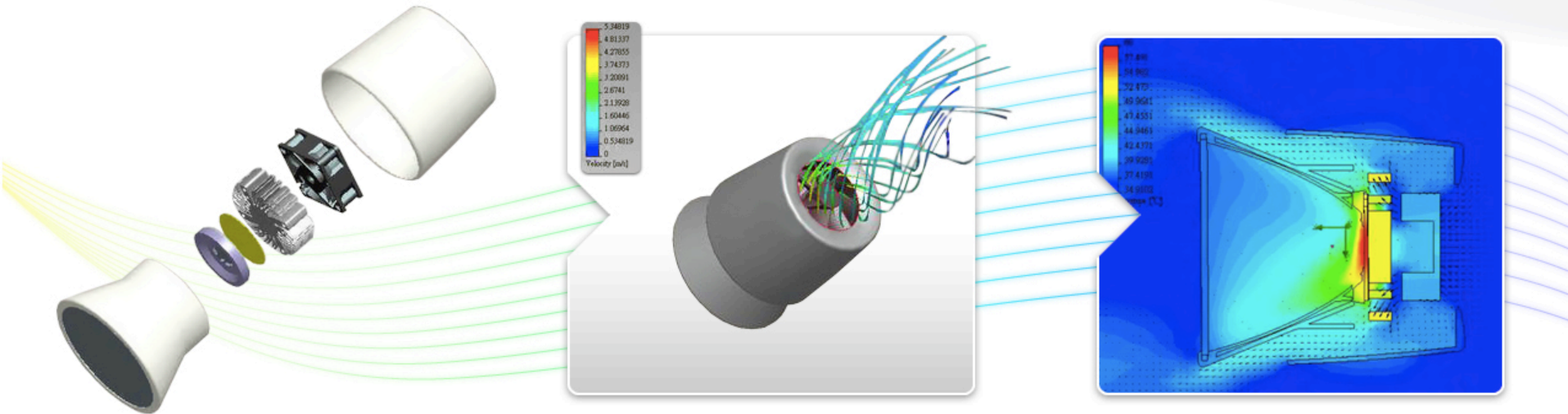
- Performance requirement cooling  $R_{th} < 1.11 \text{ } ^\circ\text{C/W}$
- Assuming passive cooling conditions:
  - Heat transfer coefficient (htc) =  $5 \text{ W/m}^2\text{K}$  and
  - Contribution  $R_{thTIM} = 0.1 \text{ } ^\circ\text{C/W}$
- A calculated cooling surface of  $0.180\text{m}^2$  is required
- This corresponds to the surface a cylinder of  $\varnothing 120\text{mm}$  and  $478\text{mm}$  long!

Goal of an active solution is to actively move air over the cooling surfaces to increase the heat transfer coefficient, therefore enabling small, compact and light weight cooling solutions (and systems)



# CFD analysis

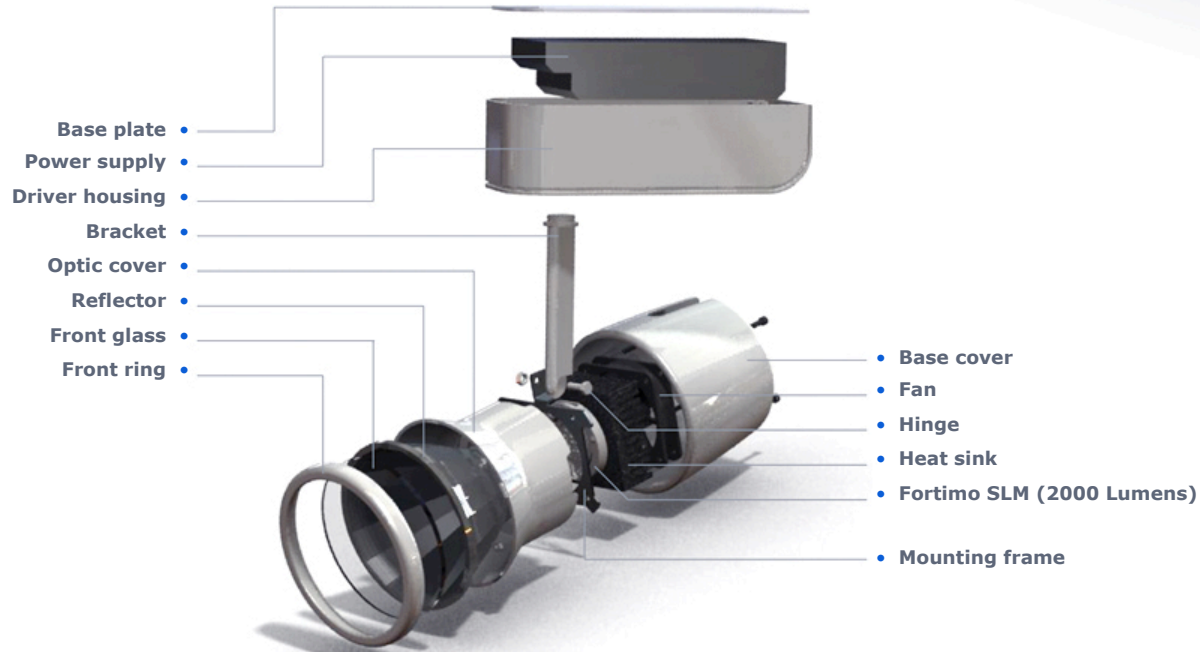
- CFD analysis can be a great way to help design a good active cooled luminaire
- A possible design is shown below
- The complete cooling solution has reduced to a small, compact and light weight solution of  $\varnothing 70\text{mm}$  and 40mm in height



# Active cooled luminaire designs

- Goal of an active solution is to actively move air over the cooling surfaces to increase the heat transfer coefficient, therefore enabling small, compact and light weight cooling solutions (and systems)

After optimization an active cooled luminaire design could look like this:



# Some design guidelines for active cooling

Design considerations for active cooling are:

- Provisions in luminaire design for inlet and outlet of respectively cool and hot air
- Ensure smooth airflow from inlet to outlet and prevent restrictions in the flow path (to limit vibration, recirculation and possible noise)

Always take care to:

- Design for reliability (dusty environments)
- Design for performance (differentiator)
- Design for low noise (differentiator)

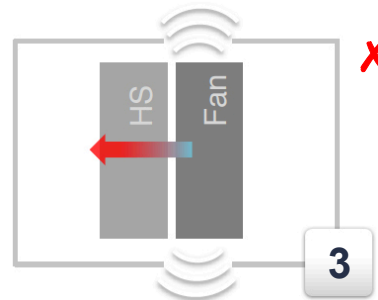
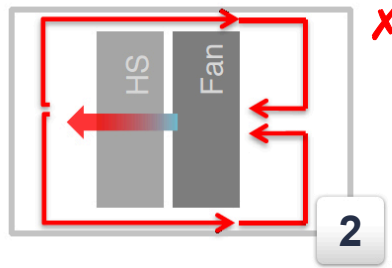
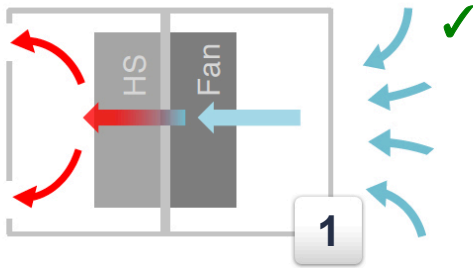




# Some design guidelines for active cooling

Design considerations for active cooling are:

- Provisions in luminaire design for inlet and outlet of respectively cool and hot air (1) Ensure smooth airflow from inlet to outlet and prevent restrictions in the flow path (to limit vibration recirculation and possible noise)
- Avoid recirculation of hot air (2) inside the luminaire, which leads to lower thermal performance and higher noise level.
- Enclose fan noise avoiding unnecessary openings near the fan in the luminarie's housing (3)



# Thermal solution validation

When testing the thermal performance of your luminaire pay special attention to these 2 numbers!

- Max temperature of the module  $T_c = 65^\circ\text{C}$
- Max  $\Delta T$   $30^\circ\text{C}$  ( $T_c = 65^\circ\text{C}$  when your ambient temperature is  $35^\circ\text{C}$ )

Operating the system under those parameters will guarantee its proper performance in terms of:

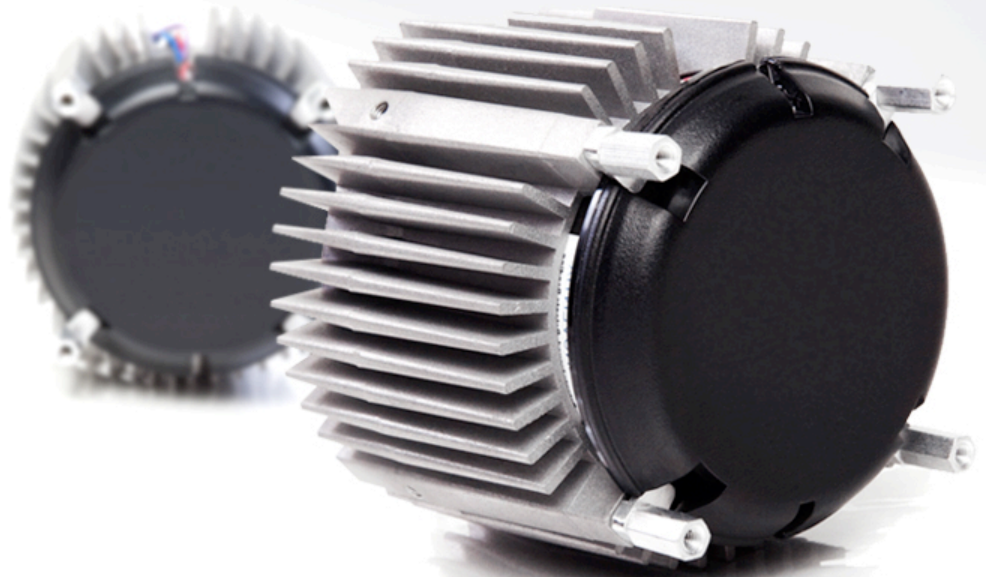
- Lumen output
- Light consistency
- Life time

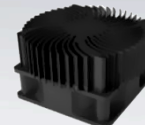
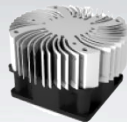
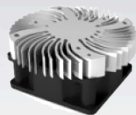


# Complementary partners for thermal solutions

Overview of our complementary partners and their cooling solutions that are especially designed for the Fortimo SLM platform

- AVC (active and passive solutions)
- Sunon (active solutions)
- Nuventix (active solutions)
- Wisefull (active solutions)
- FrigoDynamics (passive solutions)





Module Type	Fortimo SLM 800Lm Passive Solution	Fortimo SLM 1100Lm Passive Solution + ø9mm heatpipe	Fortimo SLM 1100Lm Active Solution	Fortimo SLM Lexel 1500Lm Active Solution	Fortimo SLM 2000Lm Active Solution	Fortimo SLM 3000Lm Active Solution
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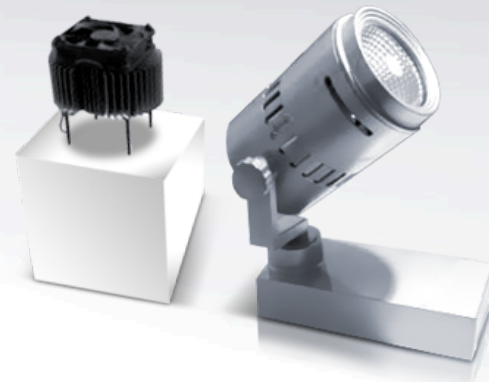
Heatsink Type	Sunflower Heatsink	Sunflower Heatsink	Sunflower Heatsink	Sunflower Heatsink	Sunflower Heatsink	Sunflower Heatsink
Heatsink Model	FSLM-PI1000-I	FSLM-HP1100	FSLM-A1100-G1	FSLM-ALexel-G1	FSLM-A2000-G2	FSLM-A3000-G3
Total Height (Heatsink + module)		105mm	30mm	40mm	40mm	40mm
Heatsink Geometry	Extrusion	Extrusion	Extrusion	Extrusion	Extrusion	Extrusion
Heatsink Dimensions	ø70mm*H30mm	ø100mm*H105mm	ø65mm*H10mm	ø65mm*20mm	ø70mm*20mm	ø75mm*H50mm
Dimensions Weight (kg)		0.685	0.080	0.128	0.150	TBC
Heatsink Material	AL6063-T5	AL6063-T5	AL6063-T5	AL6063-T5	AL6063-T5	AL6063-T5
Surface finish	Black Anodized	Anodized	Anodized	Anodized	Black Anodized	Black Anodized
LED Thermal Power	10W	17W	17W	18W	31W	40W
Ambient Temperature	35°C	35°C	35°C	35°C	35°C	35°C
Case Temperature	<=65°C	<=65°C	<=65°C	<=65°C	<=65°C	<=65°C
Thermal Resistance	<3°C/W	<1.75°C/W	<1.75°C/W	<1.65°C/W	<0.95°C/W	<0.95°C/W
Lower-noise FAN	N/A	N/A	DS0520_12L	DS0520_12L	DS6020_12E	DS0715
Fan dimensions	N/A	N/A	50mm*50mm*H20mm	50mm*50mm*H20mm	60mm*60mm*H20mm	70mm*70mm*H15mm
Fan rated voltage	12V	N/A	12VDC	12VDC	12VDC	12VDC
Fan Noise Level	N/A	N/A	<21dB	<21dB	<21dB	<21dB
Fan RPM speed	N/A	N/A	3000RPM±15%	3000RPM±15%	2200RPM±15%	2200RPM±15%
Thermal interfaces materials	TIG780-50	TIG780-50	TIG780-50	TIG780-50	TIG780-50	TIG780-50



LED Fortimo SLM 2000Lm  
 LED Power 31W  
 Cooling Module Model No.TA003-I0001  
 Cooling Module Diameter  $\varnothing 86 \times 37 \text{mm}$   
 Fan Dimension  $60 \times 60 \times 15 \text{mm}$   
 Fan Rating Voltage 12VDC  
 Fan Rating Current 24mA  
 Fan Speed 2200RPM  
 Cooling Module Noise @ 1M 18dB(A)  
 Heat Sink Material Aluminum  
 Weight 235g



SLM 2000Lm gen 2 (TA003-I0003) solution  
 improved for use in track luminaires



SLM 3000lm (TA004-I0003)  
 • Prototypes available  
 • Limited engineering samples available  
 end march 2011  
 • MP release in April 2011

**SLM 1100Lm + SLM 1500Lm also to be released March April**

- Solution for SLM 800Lm, 1100Lm and 1500Lm
- Solution for SLM 2000Lm, 3000Lm recommended for open air applications, for track applications design-in guidelines of Nuventix to be followed to ensure performance, assess case by case

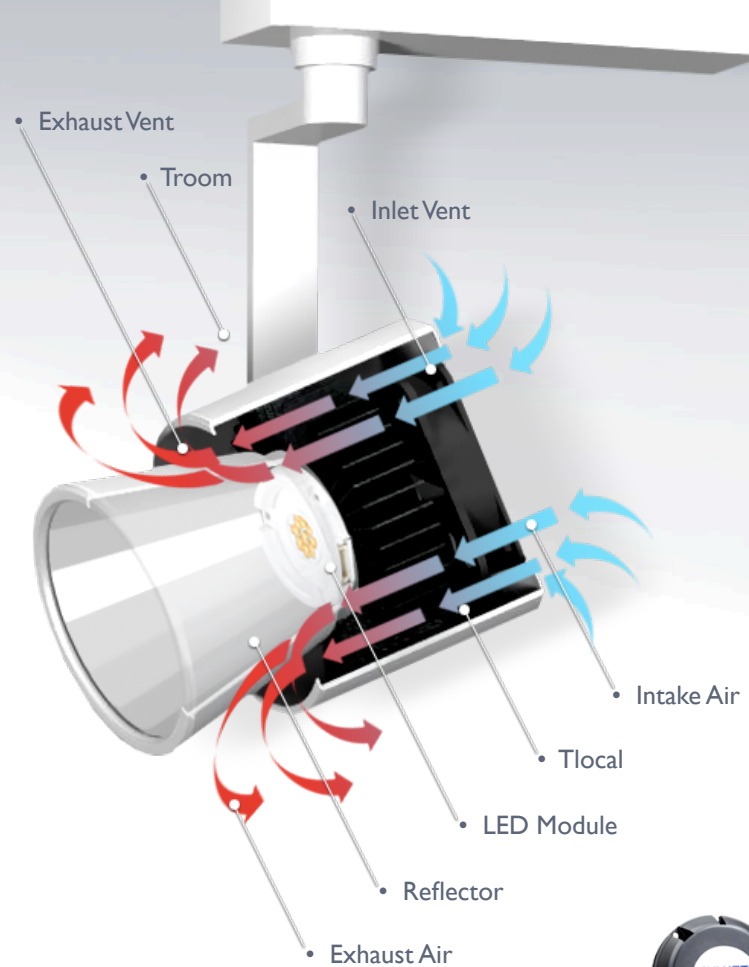


Track and Recessed Applications	Spotlight Cooler 38W Standard	Spotlight Cooler 34W High Performance	Spotlight Cooler 34W Mid Performance	Spotlight Cooler 34W Standard	Spotlight Cooler 31W High Performance	Spotlight Cooler 31W Mid Performance	Spotlight Cooler 31W Standard	Spotlight Cooler 21W Standard
Fortimo LED SLM 1100 840, Tamb = 35°C	✓	✓	✓	✓	✓	✓	✓	✓
Fortimo LED SLM 1100 835, Tamb = 35°C	✓	✓	✓	✓	✓	✓	✓	✓
Fortimo LED SLM 1100 830, Tamb = 35°C	✓	✓	✓	✓	✓	✓	✓	✓
Fortimo LED SLM 2000 840, Tamb = 35°C	✓	✓	✓	✓	✓			
Fortimo LED SLM 2000 835, Tamb = 35°C	✓	✓	✓	✓	✓			
Fortimo LED SLM 2000 830, Tamb = 35°C	✓	✓	✓	✓	✓			

# SynJet<sup>®</sup> Airflow Basics

## Enclosure Guidelines

- Inlet vents can either be on back, sides or both
- Exhaust vents can be on sides, front or both
- Vents should be designed to allow maximum airflow into and out of the enclosure
- $T_{\text{room}}$  is the temperature around the outside of the fixture far enough removed to not be impacted by fixture
- $T_{\text{local}}$  is the temperature within the fixture near the nozzles and is higher in temperature than  $T_{\text{room}}$
- Enclosure should be designed to minimize the difference between  $T_{\text{room}}$  and  $T_{\text{local}}$





## Active solution



	Sample	Testing time (min)	Temperature (°C)		$\Delta T(^{\circ}\text{C})$	$R_{th}(^{\circ}\text{C/W})$
			Ta	Tc		
1#	Run 1 (Free air, downward lighting direction)	30	23.9	45.4	21.5	0.693
	Run 2 (free air, upward lighting direction)	30	24.0	47	23	0.742
	Run 3 (Test in luminaire, 5mm air exit width)	60	23.8	59.7	35.9	1.159
	Run 4 (Test in luminaire, 10mm air exit width)	60	24.2	56.4	32.2	1.039
2#	Run 1	30	23.7	44.7	21	0.677
	Run 2	30	24.1	46.8	22.7	0.732
	Run 3	30	24.6	60.4	35.8	1.155
	Run 4	30	23.9	56.3	32.4	1.045

Note:  $R_{th}$  is calculated by using 31W as the assumed heat dissipation

## But also Passive



P/N WF1006-16-24  
For Philips Fortimo LED SLM 1100Lm

LED Power: 17W  
Thermal resistance: 1.584  $^{\circ}\text{C/W}$   
Material: AL6063  
Weight: 417g  
Dimension:  $\varnothing 110\text{mm} \times 65\text{mm}$   
Finish: Black anodize

### Thermal solutions for Philips LED module

Solutions for SLM 800lm, 1100lm and 1500lm

*Solution for SLM 2000lm only suitable in free air*

# Frigo Dynamics GmbH

- Tested solution suitable for SLM 800lm, 1100lm and 1500lm in free air

**Please contact FrigoDynamics for commercial information**



# Contact information complementary partners 1/2

## Cooling solutions

Headquarter AVC Kaohsiung  
No.248-27, Hsin-Sheng Rd.,  
80672 Kaohsiung City, Taiwan

Contact person for Europe  
Beatrice Tseng  
Phone: +31 208932195  
Cell: +31 646688175  
E-mail: [beatrice\\_tseng@avc.com.tw](mailto:beatrice_tseng@avc.com.tw)

Contact person for N.A. & Asia  
Jeff Chou  
Phone: +86-21-50270508 ext. 68528  
Cell: +86 13916680014  
E-mail: [jeff\\_chou@avc.com.cn](mailto:jeff_chou@avc.com.cn)

Sunonwealth Electric Machine Industry Co.,  
Ltd  
No.30, Lane 296 Shin-YaRoad,  
Chyan-JennDt., Kaohsiung 806,  
Taiwan

Contact person for Europe  
Alipio Marques  
Phone: +33 146 154 494  
Cell: +33 616 795 314  
E-mail: [alipio.marques@sunon.fr](mailto:alipio.marques@sunon.fr)

Contact person for Asia  
Sandra Lin  
Phone: +886-7-813-5888 ext 1257  
Cell: +886-911-739-507  
E-mail: [sandra@email.sunon.com.tw](mailto:sandra@email.sunon.com.tw)

Corporate Headquarters Nuventix  
Worldwide Sales Office  
4635 Boston Lane  
Austin, Texas 78735  
USA

Contact person for Europe  
Francois Jaegle  
Phone: +33 624734646  
E-mail: [fjaegle@nuventix.com](mailto:fjaegle@nuventix.com)

Contact person for US  
Jeff Kelly  
Phone: +33 624734646  
E-mail: [fjaegle@nuventix.com](mailto:fjaegle@nuventix.com)

# Contact information complementary partners 2/2

## Cooling solutions

### Wisefull

[www.wisefull.com](http://www.wisefull.com)

Wisefull Technology Ltd. –

Your Reliable Thermal Partner

### Contact person

Wilson Peng

No. 3, Hong-Yeh South 9th Rd.

Hong-Yeh I 38 Industrial Park, Tang Xia Town,  
Dongguan City, Guangdong Province, P.R. China

Email: [weihua@wisefull.com](mailto:weihua@wisefull.com)

Tel: (86)76987725315~6 Ext: 678

Fax: (86) 76986853535

Mobile: (86)13926896210

### Frigo Dynamics GmbH

Bahnhofstr. 16

D-85570 Markt-Schwaben

Germany

### Contact person

Hans Kunstwadt

Email: [h.kunstwadt@frigodynamics.com](mailto:h.kunstwadt@frigodynamics.com)

Tel: +49-8121-973730

Fax: +49-8121-973731

Mob: +49-171-6505418



